

What is claimed is:

1. A light emitting diode (LED) comprising a light emitting chip, a positive finger, a negative finger and a sealed housing, wherein the light emitting chip is disposed at the negative finger; and being
5 characterized that, the sealed housing at an exterior of the light emitting chip has an upper portion thereof as transparent epoxy and a lower portion thereof as an inorganic material having a high thermal conductance coefficient.
2. The LED in accordance with claim 1, wherein the inorganic material
10 is silicon carbide (SiC).
3. The LED in accordance with claim 1, wherein the inorganic material is aluminum nitride (AlN).
4. The LED in accordance with claim 1, wherein the inorganic material is beryllium oxide (BeO).
- 15 5. The LED in accordance with claim 1, wherein the inorganic material is boron nitride (BN).
6. The LED in accordance with claim 1, wherein the inorganic material is an artificial diamond.